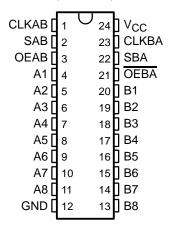
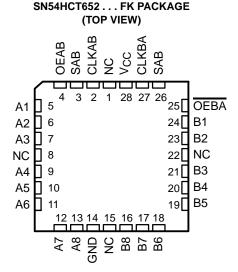
SCLS179D - MARCH 1984 - REVISED MARCH 2003

- Operating Voltage Range of 4.5 V to 5.5 V
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 12 ns
- ◆ ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible

SN54HCT652...JT OR W PACKAGE SN74HCT652...DW OR NT PACKAGE (TOP VIEW)



- Independent Registers and Enables for A and B Buses
- Multiplexed Real-Time and Stored Data
- True Data Paths
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads



NC - No internal connection

description/ordering information

The 'HCT652 devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. Output-enable (OEAB and \overline{OEBA}) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select real-time or stored data transfer. A low input level selects real-time data; a high input level selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with these devices.

ORDERING INFORMATION

| TA | PACKAGE [†] | | ORDERABLE PART NUMBER | TOP-SIDE Marking |
|----------------|----------------------|---------------|--------------------------|---------------------|
| | PDIP – NT | Tube | SN74HCT652NT | SN74HCT652NT |
| –40°C to 85°C | SOIC - DW | Tube | SN74HCT652DW | HCT652 |
| | 30IC - DW | Tape and reel | SN74HCT652DWR | HC1032 |
| | CDIP – JT | Tube | SNJ54HCT652JT | SNJ54HCT652JT |
| –55°C to 125°C | CFP – W | Tube | SNJ54HCT652W | SNJ54HCT652W |
| | LCCC – FK | Tube | SNJ54HCT652FK | SNJ54HCT652FK |

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SN54HCT652, SN74HCT652 **OCTAL BUS TRANSCEIVERS AND REGISTERS** WITH 3-STATE OUTPUTS

SCLS179D - MARCH 1984 - REVISED MARCH 2003

description/ordering information (continued)

Data on the A or B data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) terminals, regardless of the select- or output-control terminals. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

To ensure the high-impedance state during power up or power down, OEBA should be tied to V_{CC} through a pullup resistor and OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

FUNCTION TABLE

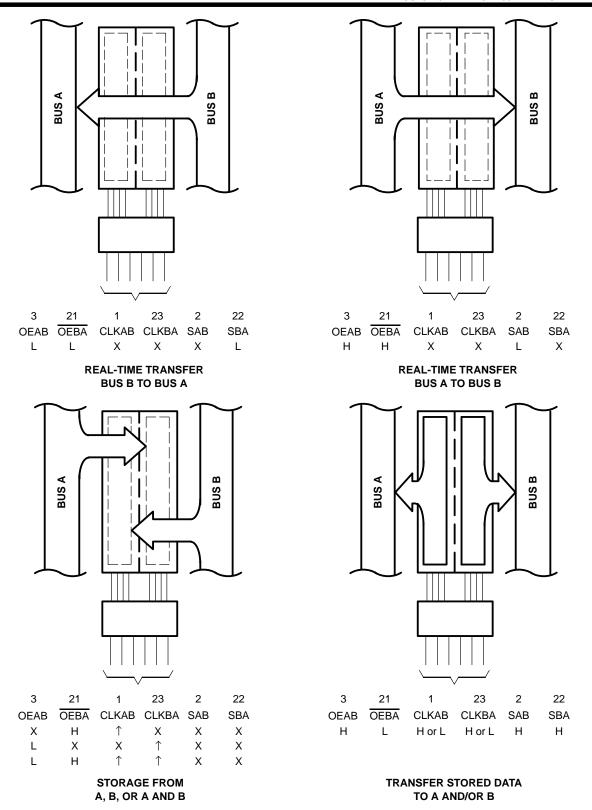
| | | INPU ⁻ | гs | | | DATA | A 1/0† | OPERATION OR FUNCTION |
|------|------|-------------------|--------|-----|-----|--------------------------|--------------------------|---|
| OEAB | OEBA | CLKAB | CLKBA | SAB | SBA | A1-A8 | B1-B8 | OPERATION OR FUNCTION |
| L | Н | H or L | H or L | Х | Х | Input | Input | Isolation |
| L | Н | ↑ | 1 | X | X | Input Input | | Store A and B data |
| Х | Н | ↑ | H or L | Х | Х | Input | Unspecified [‡] | Store A, hold B |
| Н | Н | ↑ | 1 | X‡ | X | Input | Output | Store A in both registers |
| L | Х | H or L | 1 | Х | Х | Unspecified [‡] | Input | Hold A, store B |
| L | L | ↑ | 1 | X | χ‡ | Output | Input | Store B in both registers |
| L | L | Х | Х | Х | L | Output | Input | Real-time B data to A bus |
| L | L | Χ | H or L | X | Н | Output | Input | Stored B data to A bus |
| Н | Н | Х | Х | L | Х | Input | Output | Real-time A data to B bus |
| Н | Н | H or L | Χ | Н | X | Input | Output | Stored A data to B bus |
| Н | L | H or L | H or L | Н | Н | Output | Output | Stored A data to B bus and stored B data to A bus |

[†] The data-output functions can be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition on the clock inputs.



[‡] Select control = L: clocks can occur simultaneously.

Select control = H: clocks must be staggered to load both registers.



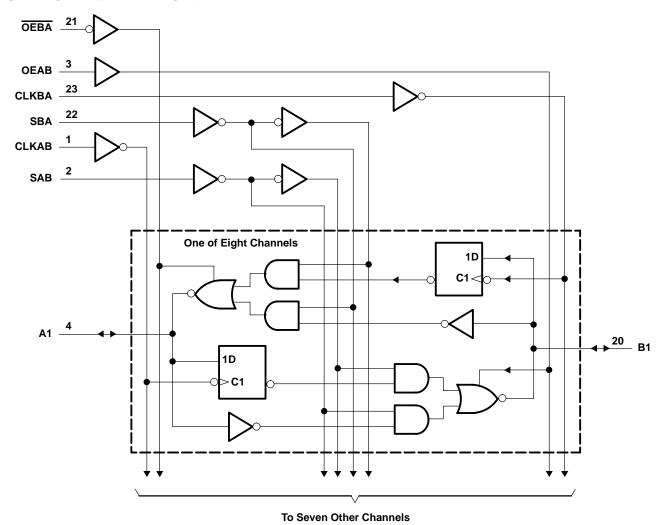
Pin numbers shown are for the DW, JT, NT, and W packages.

Figure 1. Bus-Management Functions



SCLS179D - MARCH 1984 - REVISED MARCH 2003

logic diagram (positive logic)



Pin numbers shown are for the DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| Supply voltage range, V _{CC} | –0.5 V to 7 V |
|--|---------------|
| Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC}) (see Note 1) | ±20 mA |
| Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1) | ±20 mA |
| Continuous output current, I_O ($V_O = 0$ to V_{CC}) | |
| Continuous current through V _{CC} or GND | ±70 mA |
| Package thermal impedance, θ _{JA} (see Note 2): DW package | |
| (see Note 3): NT package | |
| Storage temperature range, T _{stg} | |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-3.



SCLS179D - MARCH 1984 - REVISED MARCH 2003

recommended operating conditions (see Note 4)

| | | | SN | 54HCT6 | 52 | SN | 74HCT6 | 52 | UNIT |
|----------------|---------------------------------------|--|-----|--------|-----|-----|--------|-----|------|
| | | | MIN | NOM | MAX | MIN | NOM | MAX | UNIT |
| Vcc | Supply voltage | | 4.5 | 5 | 5.5 | 4.5 | 5 | 5.5 | V |
| VIH | High-level input voltage | V _{CC} = 4.5 V to 5.5 V | 2 | | 15 | 2 | | | V |
| VIL | Low-level input voltage | $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$ | | PE A | 0.8 | | | 0.8 | V |
| VI | Input voltage | | 0 | 7 | Vcc | 0 | | VCC | V |
| ٧o | Output voltage | | 0 | 5 | Vcc | 0 | | VCC | V |
| t _t | Input transition (rise and fall) time | | Ċ | 7 | 500 | | | 500 | ns |
| TA | Operating free-air temperature | · | -55 | | 125 | -40 | | 85 | °C |

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| | RAMETER | TEST CO | NDITIONS | | Т | A = 25°C | ; | SN54H | CT652 | SN74H | CT652 | UNIT |
|-----------|----------------|--|--|-------------------|------|----------|------|-------|-------|-------|-------|------|
| PARAMETER | | 1231 00 | vcc | MIN | TYP | MAX | MIN | MAX | MIN | MAX | UNII | |
| Vон | | VI = VIH or VIL | $I_{OH} = -20 \mu A$ | 4.5 V | 4.4 | 4.499 | | 4.4 | | 4.4 | | V |
| VOH | | VI = VIH OI VIL | $I_{OH} = -6 \text{ mA}$ | 4.5 V | 3.98 | 4.3 | | 3.7 | | 3.84 | | V |
| Va. | | \/ı = \/ or \/ | $I_{OL} = 20 \mu A$ | 4.5 V | | 0.001 | 0.1 | | 0.1 | | 0.1 | V |
| VOL | | VI = VIH or VIL | $I_{OL} = 6 \text{ mA}$ | 4.5 V | | 0.17 | 0.26 | | 0.4 | | 0.33 | ٧ |
| Ιį | Control inputs | $V_I = V_{CC}$ or 0 | | 5.5 V | | ±0.1 | ±100 | | ±1000 | | ±1000 | nA |
| loz | A or B | $V_O = V_{CC}$ or 0, Data = V_{CC} or 0 | · · · · · · · · - | 5.5 V | | ±0.01 | ±0.5 | 200 | ±10 | | ±5 | μΑ |
| Icc | | $V_I = V_{CC}$ or 0, | I _O = 0 | 5.5 V | | | 8 | 30, | 160 | | 80 | μΑ |
| ∆lcc† | † | | One input at 0.5 V or 2.4 V, Other inputs at 0 or V _{CC} | | | 1.4 | 2.4 | Yd | 3 | | 2.9 | mA |
| Ci | Control inputs | | | 4.5 V to 5.5 V | | 3 | 10 | | 10 | | 10 | pF |

[†] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or VCC.

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

| | | V | T _A = 2 | 25°C | SN54H | CT652 | SN74H | CT652 | UNIT |
|-----------------|---|-------|--------------------|------|-------|-------|-------|-------|---------|
| | | VCC | MIN | MAX | MIN | MAX | MIN | MAX | UNIT |
| f | Clock frequency | 4.5 V | | 25 | | 17 | | 20 | MHz |
| fclock | Clock frequency | 5.5 V | | 28 | | 19 | | 22 | IVII IZ |
| | Pulse duration, CLKBA or CLKAB high or low | 4.5 V | 20 | | 30 | A. | 25 | | ns |
| t _W | Pulse duration, CERBA of CERAB High of low | 5.5 V | 18 | | 27 | Q' | 23 | | 115 |
| | Output time. A hadron Olikaph on B hadron Olikaph | 4.5 V | 15 | | 23 | | 19 | | 20 |
| t _{su} | Setup time, A before CLKAB↑ or B before CLKBA↑ | 5.5 V | 14 | | 21 | | 17 | | ns |
| +. | Hold time, A after CLKAB↑ or B after CLKBA↑ | 4.5 V | 5 | | 5 | | 5 | | ne |
| th | HOID LITTLE, A AILET CLAAD TOT B AILET CLABAT | 5.5 V | 5 | | 5 | | 5 | | ns |

SN54HCT652, SN74HCT652 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCLS179D - MARCH 1984 - REVISED MARCH 2003

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

| DADAMETED | FROM | то | V | T, | գ = 25°C | ; | SN54H | CT652 | SN74H | CT652 | LINUT |
|------------------|----------------------|----------|-------|-----|----------|-----|-------|-------|-------|-------|--------|
| PARAMETER | (INPUT) | (OUTPUT) | VCC | MIN | TYP | MAX | MIN | MAX | MIN | MAX | UNIT |
| f | | | 4.5 V | 25 | 35 | | 17 | | 20 | | MHz |
| f _{max} | | | 5.5 V | 28 | 40 | | 19 | | 22 | | IVITIZ |
| | CLKBA or CLKAB | A or B | 4.5 V | | 18 | 36 | | 54 | | 45 | |
| | CLNDA OI CLNAD | AUIB | 5.5 V | | 16 | 32 | | 49 | | 41 | |
| 4 . | A or B | B or A | 4.5 V | | 14 | 27 | | 41 | | 34 | |
| ^t pd | AUIB | | 5.5 V | | 12 | 24 | | 37 | | 31 | ns |
| | 004 04D [†] | A or B | 4.5 V | | 20 | 38 | 6 | 57 | | 48 | |
| | SBA or SAB† | | 5.5 V | | 17 | 34 | 72 | 51 | | 43 | |
| | | A or B | 4.5 V | | 25 | 49 | 0 | 74 | | 61 | |
| ^t en | OEBA or OEAB | AUIB | 5.5 V | | 22 | 44 | Q | 67 | | 55 | ns |
| 4 | OFAR | A or D | 4.5 V | | 25 | 49 | | 74 | | 61 | |
| ^t dis | tdis OEBA or OEAB | A or B | 5.5 V | | 22 | 44 | | 67 | | 55 | ns |
| | | A m. r | 4.5 V | | 9 | 12 | | 18 | | 15 | |
| t _t | | Any | 5.5 V | | 7 | 11 | | 16 | | 14 | ns |

[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 2)

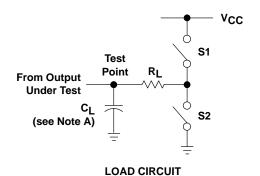
| PARAMETER | FROM | то | V | T, | չ = 25°C | ; | SN54H | CT652 | SN74H | CT652 | LINIT | |
|-----------------|----------------------|----------|--------|-------|----------|-----|-------|-------|-------|-------|-------|--|
| PARAMETER | (INPUT) | (OUTPUT) | VCC | MIN | TYP | MAX | MIN | MAX | MIN | MAX | UNIT | |
| | CLKBA or CLKAB | A D | 4.5 V | | 24 | 53 | | 80 | | 66 | | |
| | CLNDA OF CLNAD | A or B | 5.5 V | | 22 | 47 | | 72 | | 60 | | |
| | A or B | B or A | 4.5 V | 22 44 | | | | 70 | | 55 | | |
| ^t pd | AUIB | BULA | 5.5 V | | 20 | 39 | | 60 | | 50 | ns | |
| | 004 045 [±] | A or D | A or D | 4.5 V | | 26 | 55 | | 83 | | 69 | |
| | SBA or SAB† | A or B | 5.5 V | | 24 | 49 | 2 | 74 | | 62 | | |
| | | A D | 4.5 V | | 33 | 66 | 0 | 100 | | 82 | | |
| ^t en | OEBA or OEAB | A or B | 5.5 V | | 30 | 59 | Q | 90 | | 74 | ns | |
| | A | | 4.5 V | | 17 | 42 | | 63 | | 53 | | |
| t _t | | Any | 5.5 V | | 14 | 38 | | 57 | | 48 | ns | |

[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

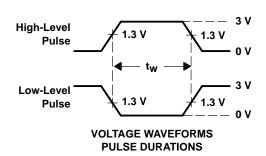
operating characteristics, T_A = 25°C

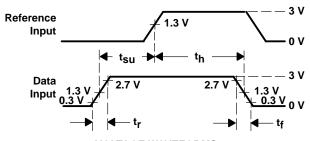
| ĺ | | PARAMETER | TEST CONDITIONS | TYP | UNIT |
|---|-----------------|-------------------------------|-----------------|-----|------|
| | C _{pd} | Power dissipation capacitance | No load | 50 | pF |

PARAMETER MEASUREMENT INFORMATION

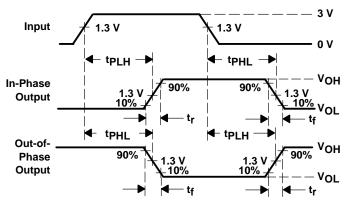


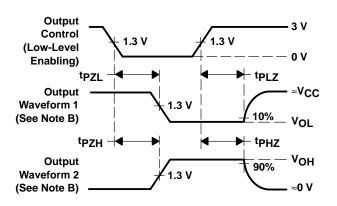
| PARA | METER | RL | CL | S1 | S2 |
|-----------------------------------|-------|----------------|-----------------------|--------|--------|
| | tPZH | 1 kO | 50 pF | Open | Closed |
| t _{en} | tPZL | 1 kΩ or 150 pF | | Closed | Open |
| | tPHZ | 1 k Ω | 50 pF | Open | Closed |
| ^t dis | tPLZ | 1 K22 | 30 pr | Closed | Open |
| t _{pd} or t _t | | _ | 50 pF or 150 pF | Open | Open |





VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT RISE AND FALL TIMES

VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_\Gamma = 6 \ ns$, $t_f = 6 \ ns$.
- D. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpl 7 and tpH7 are the same as tdis.
- G. tpzL and tpzH are the same as ten.
- H. tpLH and tpHL are the same as tod.

Figure 1. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | e Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|-----------------|--------------------|------|----------------|---------------------------|------------------|------------------------------|
| SN74HCT652DW | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74HCT652DWE4 | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74HCT652DWG4 | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74HCT652DWR | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74HCT652DWRE4 | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74HCT652DWRG4 | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74HCT652NT | ACTIVE | PDIP | NT | 24 | 15 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74HCT652NTE4 | ACTIVE | PDIP | NT | 24 | 15 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





| | Dimension designed to accommodate the component width |
|----|---|
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | | Package Drawing | | | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|------|--------------------|----|------|--------------------------|--------------------------|---------|---------|---------|------------|-----------|------------------|
| SN74HCT652DWR | SOIC | DW | 24 | 2000 | 330.0 | 24.4 | 10.75 | 15.7 | 2.7 | 12.0 | 24.0 | Q1 |





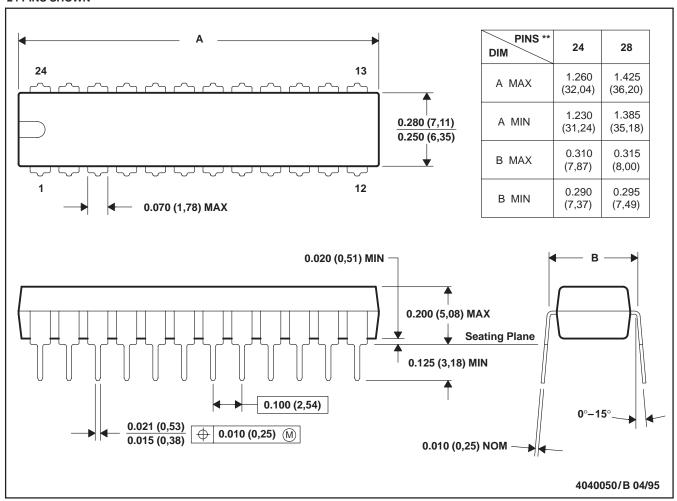
*All dimensions are nominal

| ĺ | Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| I | SN74HCT652DWR | SOIC | DW | 24 | 2000 | 346.0 | 346.0 | 41.0 |

NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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